

[BUMP-FORMING PROCESS]

Abstract

A bump-forming process is provided. An adhesion layer is formed on an active surface of a wafer. A barrier layer and a wettable layer are sequentially formed over the adhesion layer. A portion of the wettable layer and a portion of the barrier layer are removed and then a patterned mask layer is formed over the adhesion layer. The mask layer has a plurality of openings that at least exposes the wettable layer. A printing process is performed to deposit solder paste into the openings. Thereafter, a reflow process is carried out so that the solder paste inside the openings is transformed into bumps. The mask layer is removed, followed by removing the adhesion layer outside the residual wettable layer and the residual barrier layer.